| 100 | processing system |
|------|---|
| 102 | plasma etching system |
| 104 | process monitor system |
| 106 | chamber |
| 108 | plasma etch system controller |
| 110 | recipe control port |
| 112 | first control bus |
| 114 | viewport |
| 116 | plasma electromagnetic emissions |
| 118 | plasma |
| 120 | spectro-meter |
| 122 | processor |
| 126 | electromagnetic emissions collector |
| 128 | fiber optic cable |
| 130 | second control bus |
| 132 | user |
| 134 | third control bus |
| 136 | fourth control bus |
| 1000 | fifth control bus |
| 700 | calibration process |
| 702 | start calibration run |
| 704 | perform calibration process |
| 705 | start correlated OES and RF data collection |
| 706 | perturb the process |
| 708 | terminate correlated OES and RF data collection |
| 710 | identify time periods |
| | · |

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| 712 | perform PCA on collected data |
|-----|--|
| 714 | identify steady principle components |
| 716 | has the number of desired perturbation been reached? |
| 718 | determine the need for signal enhancement |
| 720 | perform OES and/or RF data enhancement |
| 722 | perform RCA on modified data |
| 724 | designate identified principle components |
| 730 | end |
| 900 | Method for automatic determination of semiconductor plasma chamber matching and source of fault by comprehensive plasma monitoring |
| 902 | start study run |
| 904 | perform calibration process |
| 905 | start correlated OES and RF data collection |
| 906 | perturb the process |
| 908 | terminate correlated OES and RF data collection |
| 910 | perform OES and/or RF data enhancement |
| 912 | perform PCA on collected data |
| 914 | identify steady principle components |
| 916 | perform inner product of correlated non-reference PCs |
| 918 | has the number of desired perturbation been reached? |

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| 920 | matching scores pass matching control limit? |
|------|---|
| 922 | chamber matched |
| 924 | chamber not matched |
| 1100 | chamber fault diagnosis method |
| 1102 | start fault diagnosis run |
| 1104 | perform calibration process |
| 1105 | start correlated OES and RF data collection |
| 1106 | perturb the process |
| 1108 | terminate correlated OES and RF data collection |
| 1110 | perform OES and/or RF data enhancement |
| 1112 | perform PCA on collected data |
| 1114 | identify steady principle components |
| 1116 | perform inner product of correlated, non-reference PCs |
| 1118 | has the number of desired perturbation been reached? |
| 1120 | compare all matching scores |
| 1122 | verify if the perturbed parameter(s) of the lowest score(s) is/are the source(s) of fault |
| 1200 | source(s) of fault diagnosis method |
| 1202 | start source(s) of fault matching |
| 1204 | retrieve the PCs of the perturbed parameters |
| 1206 | search the library |
| 1208 | perform inner product of PCs of the |

| | chamber under study |
|------|---|
| 1210 | matching scores pass matching control limit? |
| 1212 | are there more stored diagnosis runs to match? |
| 1214 | source(s) of fault possibly similar to the matched diagnosis run retrieved from the library |
| 1216 | no matching found case needs to studied by expert |

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